

Product Change Notice (PCN)

Subject: Package assembly site addition for RZ/A1L (208pinLQFP)

Publication Date: 6/23/2025

Effective Date: 1/7/2026

Revision Descriptions: Initial release

Change Descriptions:

Renesas will add an assembly site for RZ/A1L (208pinLQFP) to realize stable supply.

The Booking part numbers will be changed for identification because a part of package outline will also be changed from the current product.

In addition, at the additional assembly site, The Storage Conditions After Opening Moisture-Proof Packing will be changed from Humidity $\leq 70\%$ RH to Humidity $\leq 60\%$ RH.

Table:

1010101			
Items	Additional site	Current site	
Company	Υ	Υ	
Location	Taiwan	Japan	

Affected Product List:

Added products	Current products
R7S721021VCFP#AA2	R7S721021VCFP#AA1
R7S721021VCFP#BA2	R7S721021VCFP#BA1

Reason for Changes:

For stable supply of the product.

Impact on Fit, Form, Function, Quality & Reliability:

Form : Drawings of the current product and additional product are shown in the appendix.

Package outline is considered equivalent.

Fit : No Impact
Function : No Impact
Quality : No Impact
Reliability : No Impact

Product Identification:

These products can be identified by package marking and packing label. (Refer to Appendix)

Oualification Status:

Now Available

Sample Availability Date:

7/31/2025

Device Material Declaration:

Please contact Renesas sales representatives.



PCN#:[EPPO-EX-25-0019-1]

Note:

- 1. Acknowledgement must be received by Renesas within 30 days or Renesas will consider the change as approved.
- 2. If timely acknowledgement is provided by Customer, then Customer shall have 90 days from the date of receipt of this PCN to make any objections to this PCN. If Customer fails to make objections to this PCN within 90 days of the receipt of the PCN then Renesas will consider the PCN changes as approved.
- 3. If customer cannot accept the PCN then customer must provide Renesas with a last time buy demand and purchase order.

For additional information regarding this notice, please contact your Renesas sales representative.

Appendix

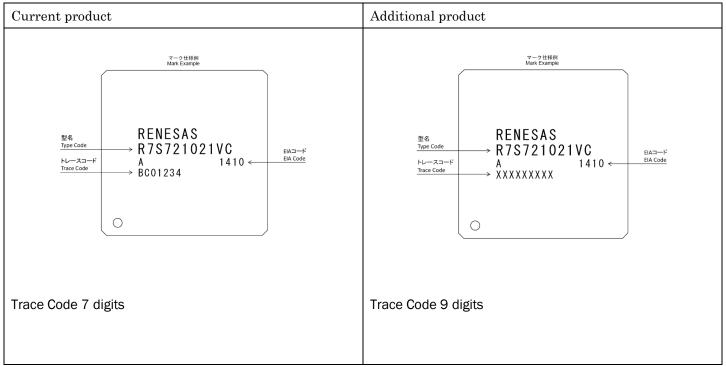
Package outline:

Current product			Additional product						
Reference Dimension in Millimeters				D C	In:		 		
Symbol	Min.	Nom.	Max.		Reference		n in Mill		
A	_	_	1. 7		Symbol	Min.	Nom.	Max.	
A1	0.05	0. 1	0. 15		A	0.05		1.7	
A2	_	1.4	_		A1	0.05		0. 15	
HD	29. 8	30	30. 2		A2	1. 35	1.4	1. 45	
D	-	28	-		<u>D</u>		30 BSC.		
HE	29. 8	30	30. 2		D1		28 BSC.		
Е	_	28	-		E		30 BSC.		
e	_	0. 5	-		E1		28 BSC.		
b	0. 17	0. 22	0. 27		N		208	_	
C	0. 095	0. 145	0. 195		e		0. 5 BSC.		
θ	0°	-	8°		b	0. 17	0. 22	0. 27	
Ī	0. 35	0. 5	0. 65		С	0. 095	_	0. 195	
L1	-	1.00	-		q	0°	3. 5°	8°	
b1	_	0. 2	_		L	0. 35	0. 5	0. 65	
c1	_	0. 125	_		L1		1.00 REF.		
X	_	0. 123	0. 08		aaa	_	_	0. 2	
V	_	_	0.08		bbb	_	_	0. 2	
ZD	_	1. 25	-		CCC	_	_	0.08	
ZE		1. 25	_		ddd	_		0.08	
Compliant J		1.20			Compliant JED	FC			
Compilant Jeila			Compitant JED	ЕС					

Storage Conditions After Opening Moisture-Proof Packing:

Current product	Additional product		
Storage after opening moisture-proof packing	Storage after opening moisture-proof packing		
Temperature 5-30°C Humidity ≤70%RH Time ≤168 hours	Temperature 5-30°C Humidity ≤60%RH Time ≤168 hours		
	There is no change to Temperature and Time.		

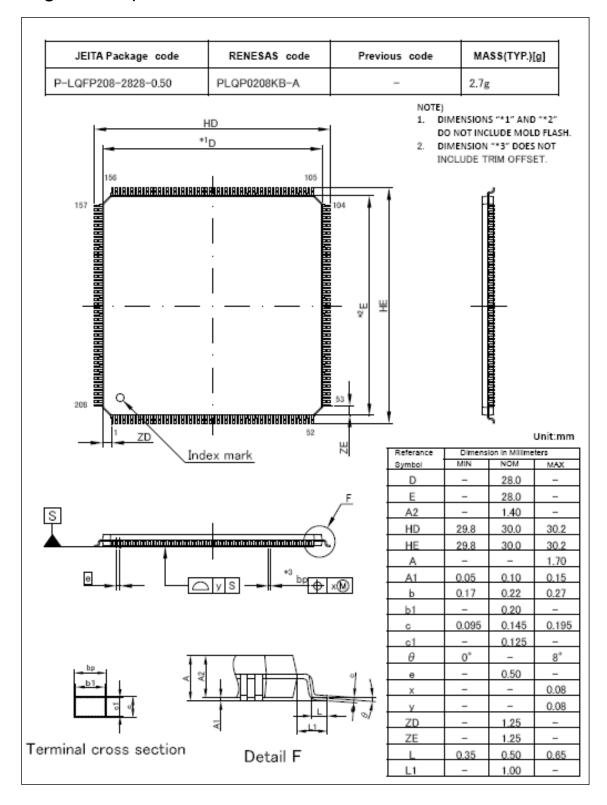
Package marking:



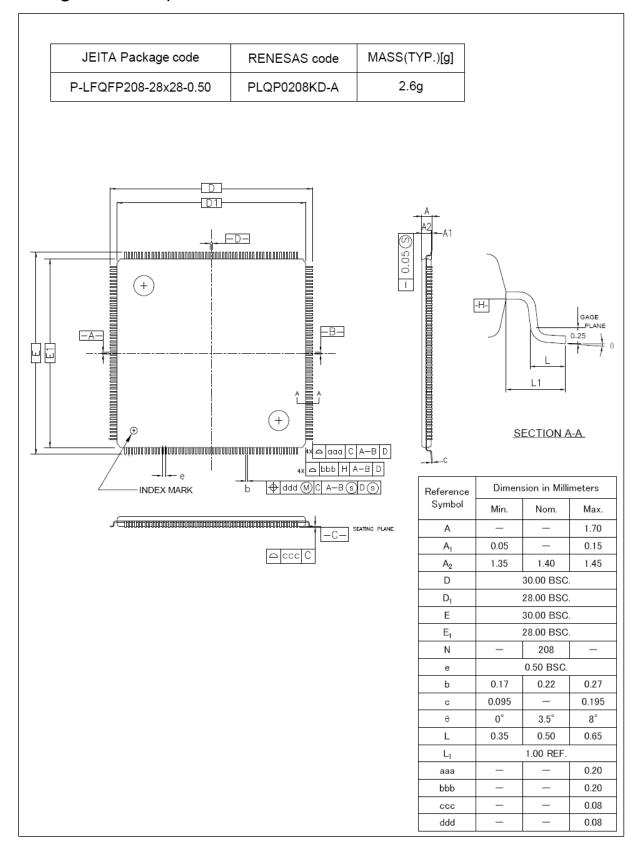
Packing label:

Current product	Additional product		
D/N: R7S721021VCFP AA1WM02000 SPN: R7S721021VCFP#AA1 AA1WM02000	D/N: R7S721021VCFP AA2M508000 SPN: R7S721021VCFP#AA2 AA2M508000 SPN order part number, The 17th digit from the left is "2".		

Outline Drawing for current product:



Outline Drawing for additional product:



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Storage Conditions After Opening Moisture-Proof Packing for current product:

実装条件 Mount Conditions	RDK-J-000062-2 1/1
防湿包装開封後保管条件 Storage Conditions After Opening Moisture-Proof Packing	ルネサス エレクトロニクス株式会社 Renesas Electronics Corporation

防湿包装開封後の保管について

Storage after opening moisture-proof packing.

防湿包装開封後はパッケージの吸湿を避けるため、下記条件にて保管してください。

After opening moisture-proof packing, semiconductor devices must be stored under the following conditions to prevent moisture absorption by the packages.

項目	条件	備考
Item	Condition	Note
温度 Temperature	5°C∼30°C 5 – 30°C	
湿度 Humidity	70%RH以下 ≦70%RH	
時間 ※ Time	168 時間以内 ≦168 hours	※開封後~最終リフローはんだ付け完了までの時間 The time from the point the packaging is opened until the last device reflowing has been completed.

Storage Conditions After Opening Moisture-Proof Packing for additional product:

実装条件 Mount Conditions

防湿包装開封後保管条件 Storage Conditions After Opening Moisture-Proof Packing

RDK-J-000148-1

1/1

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防湿包装開封後の保管について

Storage after opening moisture-proof packing

防湿包装開封後はパッケージの吸湿を避けるため、下記条件にて保管してください。

After opening moisture-proof packing, semiconductor devices must be stored under the following conditions to prevent moisture absorption by the packages.

項目	条件	備考
Item	Condition	Note
温度	5°C∼30°C	
Temperature	5 - 30°C	
湿度	60%RH 以下	
Humidity	≦60%RH	
時間 ※ Time	168 時間以内 ≦168 hours	※ 開封後〜最終リフローはんだ付け完了までの時間 The time from the point the packaging is opened until the last device reflowing has
		been completed.